

wherein a diameter of the cylindrical substrate is smaller than a width of the at least one semiconductor chip.

13. (Twice Amended) A semiconductor device, comprising:
a cylindrical substrate having wirings formed thereon; and
at least one stacked body mounted on a circumferential surface of said substrate, said stacked body including a plurality of semiconductor chips stacked one upon the other and being bent along the surface of said substrate, wherein each of said semiconductor chips has bumps, the bumps formed on one of said semiconductor chips are connected to said wirings, and a diameter of the cylindrical substrate is smaller than a width of each of the semiconductor chips.

26. (Twice Amended) A method of manufacturing a semiconductor device, comprising:
mounting at least one semiconductor chip having bumps on at least a region of a surface of a flexible substrate; and
bending said substrate into a cylindrical form,
wherein a diameter of the cylindrical substrate is smaller than a width of the at least one semiconductor chip.

--27. (New) The device according to claim 1, wherein a diameter of the cylindrical substrate is not larger than one-third of the width of the at least one semiconductor chip.

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28. (New) The device according to claim 13, wherein a diameter of the cylindrical substrate is not larger than one-third of the width of each of the semiconductor chips.

29. (New) The device according to claim 26, wherein a diameter of the cylindrical substrate is not larger than one-third of the width of the at least one semiconductor chip.

30. (New) A semiconductor module, comprising:

a cylindrical substrate having wirings formed thereon;

at least one semiconductor chip mounted on a circumferential surface of said substrate, said semiconductor chip being bent along the surface of said substrate and having bumps in contact with the wirings; and

a plurality of terminals to be connected to connectors, the terminals being formed on the cylindrical substrate and connected to the wirings.

31. (New) The module according to claim 30, wherein a diameter of the cylindrical substrate is smaller than a width of the at least one semiconductor chip.

32. (New) The device according to claim 31, wherein a diameter of the cylindrical substrate is not larger than one third of the width of the at least one semiconductor chip.

33. (New) The module according to claim 30, wherein the terminals are arranged on a peripheral portion of the substrate.